



NC600 (Sn60/Pb40)
NO CLEAN DELTA[®]
SOLDER WIRE

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Description

Flux Core

Delta® Solder Wire NC600 is a no clean formulation designed for both tin/lead and lead-free alloys, such as Sn60/Pb40. NC600 contains a synthetically refined resin and very effective activator so spreads like an RA type flux core. NC600 exhibits virtually no spattering and leaves minimal residue.

Main Features

- ❑ Designed for leaded and lead-free alloys
- ❑ Excellent wetting properties
- ❑ Clear, non-conductive residues

Technical Data (Flux Extract)

	Specification	Test Method
Color & Appearance	Light yellow opaque solid	Visual
Flux Classification	RELO	J-STD-004B
Copper Mirror	No removal of copper film	IPC-TM-650 2.3.32
Corrosion	Pass	IPC-TM-650 2.6.15
SIR	1.82 x 10 ¹¹	IPC-TM-650 2.6.3.3
Post Reflow Flux Residue	55%	TGA Analysis
Acid Value	190 - 210	IPC-TM-650 2.3.13
Flux Residue Dryness	Pass	IPC-TM-650 2.4.47
Spitting of Flux-Cored Solder	0.3%	IPC-TM-650 2.4.48
Solder Spread	100 mm ²	IPC-TM-650 2.4.46

Wire Diameter

Sn60/Pb40 NC600 Delta Solder Wire is available in a variety of diameters. The chosen diameter is based on application methods, pad size, and desired solder joint volume. Generally, the diameter of the wire should be slightly larger than the width/diameter of the joint or connection to be soldered. Below is a list of standard diameters.

Standard wire diameters

Diameter/Inch	0.125	0.092	0.062	0.050	0.040	0.032	0.028	0.025	0.020	0.015
Diameter/mm	3.18	2.33	1.57	1.27	1.01	0.81	0.71	0.63	0.51	0.38
Std.Wire Gauge	11	13	16	18	19	21	22	23	25	28
Tolerance, in.	+/-0.006	+/-0.005	+/-0.003	+/-0.002	+/-0.002	+/-0.002	+/-0.002	+/-0.002	+/-0.002	+/-0.002

Flux Percentage

Qualitek utilizes a state-of-the-art automatic wire extrusion and wire drawing machines to manufacture consistent solder. The introduction of flux core in the wire extrusion process involves continual monitoring of flux percentage to ensure minimal flux voids and irregular wire. Typical flux percentage for leaded solder is **1.1 – 3.3%**.

Physical Properties

Solder Composition

Qualitek has developed a rosin activated based core flux with alloy composition, Sn60/Pb40. Qualitek Sn60/Pb40 alloy conforms to and exceeds the impurity requirements of IPC-J-STD-006C.

Typical Analysis													
Sn	Ag	Cu	Pb	Sb	Bi	In	As	Fe	Ni	Cd	Al	Zn	Au
59.5 -60.5	0.100 Max	0.080 Max	Bal	0.200 Max	0.100 Max	0.100 Max	0.030 Max	0.020 Max	0.010 Max	0.002 Max	0.005 Max	0.003 Max	0.050 Max

	Sn60/Pb40
Melting Point, °C	183 - 188
Hardness, Brinell	16 HB
Coefficient of Thermal Expansion	23.9
Tensile Strength, kgf/cm ²	535
Tensile Elongation, %	40
Density, g/cm ³	8.50
Electrical Resistivity, (μΩ-cm)	15.3
Thermal Conductivity, W/m-K	49

Flux Residues & Cleaning

NC600 is a no clean formulation; therefore, the residues do not need to be removed for typical applications. If residue removal is desired, the use of Everklean 1005 Buffered Saponifier with a 5-15% concentration in hot 60 °C (140 °F) de-ionized water will aid in residue removal.

Storage & Shelf Life

Solder wire storage should be in a 65-80 °F environment away from direct heat. We recommend using gloves when handling solder wire directly. Solder wire has an indefinite shelf life.

Packaging

Qualitek flux-core wire and solid wire are packed in

12.5lb -box of ½ lb spools
25 lb -box of 1 lb spools
12.5kg -box of ½ kg spools
8 kg -box of 1kg spools
40 lb -box of 5 lb spools
20 lb -box of 20 lb spools

Disposal

Sn60/Pb40 NC600 leaded solder should be disposed of in accordance with local, regional, national and international regulations.

Qualitek® and Delta® are brands of Qualitek International, Inc. For Health and Safety information refer to Safety Data Sheet.